

NEPCON ASIA 2026 – Where Global Electronics Manufacturers

Source Next-Gen Production Solutions

Driven by booming AI-led innovation, advanced packaging evolution and global supply-chain realignment, the electronics manufacturing industry is undergoing profound transformation, with Asia accounting for more than 58 % of worldwide electronics production output. As Asia's premier PCBA and smart-manufacturing event rooted in Shenzhen — China's core electronics-manufacturing hub — **NEPCON ASIA 2026** will take place from October 27 to 29 at Shenzhen World Exhibition & Convention Center (Bao'an), offering global buyers an unparalleled one-stop sourcing gateway for state-of-the-art equipment, mature production solutions and next-generation manufacturing technologies.

Spanning 100,000 square meters of exhibition area, the event will assemble a high-end global exhibitor lineup, bringing together world-renowned industrial leaders including **Panasonic, ASMPT, Fuji, Yamaha, Omron, TRI, Koh Young, Kurtz Ersä and Nordson**, as well as leading Chinese brand such as **AXXON, JT, GKG, SUNEAST and Quick**. The exhibition comprehensively covers core industrial segments including PCB assembly, smart factory systems, semiconductor packaging and testing, high-speed optical modules, automotive electronics, display technologies and embodied intelligence.



200+ New Product Launches to Drive Production Line Optimization and Iteration

Fueled by frontier technologies such as AI computing infrastructure, advanced packaging and humanoid robotics, the show anticipates more than 200 product debuts targeting high-growth verticals: consumer electronics, automotive electronics, AI hardware (AI glasses, AI servers, AI terminals etc.), optical modules, solar PV, general industrial automation, mobile handsets, home appliances, computers & peripherals, new-energy equipment, smart-home devices and wearables.

Optical Module Manufacturing Process Demo Zone

NEPCON ASIA 2026 introduces the all-in-one Optical Module Manufacturing Process Demo Zone, combining live process demonstrations, industry-focused forums and precision business matchmaking. Centered on high-speed optical-module markets (800G

/1.6T /3.2T), the zone covers three critical workflows: COB packaging, module assembly and testing-and-aging. It showcases dedicated production equipment, key materials and complete mass-production workflows, enabling enterprises to enter this high-growth sector while refining optical-module production lines and plant-level operations. Concurrent high-level forums bring together major module manufacturers, equipment & material suppliers and optical-chip vendors for in-depth trend analysis and practical solution sharing.

- **2026 Computing Power Expo**

The 2026 Computing Power Expo will focus on the entire computing power industry chain, including data centers, AI chips, optical modules, server systems, massive storage, high-speed network interconnects, and computing services/leasing. This event creates a rare, dedicated platform for deep integration between the "computing power and industrial application" communities. It will feature three main forum themes: Data Centers & Industrial Deployment, Computing Power Infrastructure Technology, and Computing Services & Business Model Innovation. Leaders and elites from leading AI computing power companies will gather to discuss policy trends, demand fulfillment, infrastructure support, and scenario innovation, jointly shaping the future of electronics manufacturing and computing power applications.

- **Automotive Electronics Manufacturing Demonstration Line**

NEPCON will feature a demonstration line showcasing innovative automotive electronics manufacturing processes. It will cover four core segments: SMT/DIP placement processes, semiconductor packaging and testing, high-voltage wire harnessing, and product reliability testing. Complemented by precise sourcing matchmaking and automotive electronics forums, this initiative helps vehicle manufacturers and parts suppliers upgrade processes and yields, optimize supply chains, and achieve cost-effective mass production. Concurrently, the **Automotive-Grade Electronics Intelligent Manufacturing and Precision Process Innovation Seminar** will feature in-depth sharing on industry trends, advanced manufacturing technologies, and mass-production process solutions. It brings together experts from vehicle manufacturing, semiconductors, and automotive electronics, along with technical directors from factories, to provide professional insights for R&D planning and production line transformation.

- **Factory Facilities Zone**

This zone will gather over 50 suppliers of factory environment, operations, and green factory solutions, serving industries like electronics, semiconductors, automotive electronics, PCBs, touch displays, and high-performance materials. It facilitates green upgrades for electronics factories. Concurrent conferences on topics like energy-saving and low-carbon technologies, and green smart factory facilities, will explore new energy-saving technologies and best practices, empowering the green

transformation of the electronics manufacturing industry.

40+ Professional Forums Addressing Market Hotspots and Future Directions

The extensive conference programme covers core industry topics including smart manufacturing, 6G communications, product reliability, optical communications, low-carbon manufacturing, AI-computing deployment, automotive electronics, AI-driven automation, warehousing & intralogistics, embodied-intelligence robotics, machine vision, and emerging-market opportunities across Southeast Asia and Eastern Europe. Industry thought-leaders and academic experts share trend outlooks, development trajectories and practical case studies, building a high-impact exchange platform to inspire industry innovation.



As one of the flagship exhibitions under the Industrial Technology World Asia (ITWA) event portfolio, NEPCON ASIA 2026 runs concurrently with multiple influential specialised shows: VISION CHINA SHENZHEN, ES SHOW, ROBOTECH, AWC, FILM&TAPE SHENZHEN and C-TOUCH&DISPLAY SHENZHEN. Boasting a total exhibition area of 180,000 square meters, this multi-exhibition synergy creates a full-industry-chain industrial technology platform covering diverse upstream and downstream sectors. Specifically, NEPCON ASIA will precisely gather 70,000 professional electronics manufacturing practitioners focusing on PCBA, smart manufacturing and electronic production technologies, while the integrated ITWA exhibition cluster will attract over 170,000 cross-industry professional visitors from related industrial fields. For global international attendees, the event serves as an elite platform to witness cutting-edge manufacturing innovations from China and across Asia, establish long-term global business partnerships, explore high-quality cross-border sourcing opportunities, and capture first-hand insights into the latest trends and shifts of the global electronics manufacturing industry.



Pre-registration Now Open

Industry professionals are invited to register for NEPCON ASIA 2026, taking place October 27–29 at the Shenzhen World Exhibition & Convention Center (Bao'an) . Attendees will have the opportunity to explore the full electronics manufacturing chain in a single visit and experience cutting-edge innovation and high-end manufacturing firsthand.

Register Now: <https://ali2.infosalons.com.cn/reg/CNZ26/web/#!/en/login?track=962K8L>

Please visit official website for more information: <https://www.nepconasia.com/en-qb.html>

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